L	Hits	Search Text	DB	Time stamp
Number				
1	173	313/\$.ccls. and corrugated	USPAT;	2004/01/12
			EPO; JPO	05:46
2	42	313/\$.ccls. and corrugated and substrate	USPAT;	2004/01/12
			EPO; JPO	05:46
3	1048	313/506.ccls.	USPAT;	2004/01/12
			EPO; JPO	05:46
4	2661	corrugated and substrate and light	USPAT;	2004/01/12
			EPO; JPO	05:46
9	271	257/95.ccls.	USPAT;	2004/01/12
			EPO; JPO	05:46
10	1390	257/98.ccls.	USPAT;	2004/01/12
			EPO; JPO	05:46
5	207	corrugated and substrate and "light	USPAT;	2004/01/12
		emitting"	EPO; JPO	05:46
6	6	313/506.ccls. and (texture)	USPAT;	2004/01/12
			EPO; JPO	05:46
7	4	313/506.ccls. and (textured)	USPAT;	2004/01/12
			EPO; JPO	05:46
8	84	313/506.ccls. and (uneven)	USPAT;	2004/01/12
		·	EPO; JPO	05:46
13	820	313/504.ccls.	USPAT;	2004/01/12
			EPO; JPO	05:46
14	273	313/498.ccls.	USPAT;	2004/01/12
			EPO; JPO	05:46
11	1166	(IWATA nearl HIROSHI).in.	USPAT;	2004/01/12
			EPO; JPO	05:46
12	289	(IWATA nearl HIROSHI).in. and	USPAT;	2004/01/12
		semiconductor	EPO; JPO	05:46